

Solder Wire SAC305 No-Clean with 2.2% Flux Core 1oz Spool

Product Highlights

No-Clean Water-Washable Synthetic Flux Core

The clear, non-corrosive, non-conductive residue is meant to be left on the board. Residues that do remain are water soluble if you want to remove them. Clean with hot water at 60°C (140°F) minimum.

2.2% flux core

Made in USA from grade-A virgin metals

Halogen content: None

RoHS II and REACH compliant

Specifications

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|----------------------|-----------------------------------|
| Alloy: | Sn96.5/Ag3.0/Cu0.5 |
| Wire Diameter: | 0.020" |
| Flux Type: | No-Clean Water-Washable Synthetic |
| Flux Classification: | ROL0 |
| Melting Point: | 217-220°C (423-428°F) |
| Packaging: | 1 oz spool |

Test Results

| Test J-STD-004 or other requirements as stated | Test Requirement | Result |
|--|--|--|
| Copper Mirror | IPC-TM-650: 2.3.32 | L: No breakthrough |
| Corrosion | IPC-TM-650: 2.6.15 | L: No corrosion |
| Quantitative Halides | IPC-TM-650: 2.3.28.1 | L: <0.5% |
| Electrochemical Migration | IPC-TM-650: 2.6.14.1 | L: <1 decade drop (No-clean) |
| Surface Insulation Resistance 85°C, 85% RH @ 168 Hours | IPC-TM-650: 2.6.3.7 | L: ≥100MΩ (No-clean) |
| Visual | IPC-TM-650: 3.4.2.5 | Clear and free from precipitation |
| Conflict Minerals Compliance | Electronic Industry Citizenship Coalition (EICC) | Compliant |
| REACH Compliance | Articles 33 and 67 of Regulation (EC) No 1907/2006 | Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials |

Conforms to the following Industry Standards:

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|---|-----|
| J-STD-004B, Amendment 1 (Solder Fluxes): | Yes |
| J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): | Yes |
| RoHS 2 Directive 2011/65/EU: | Yes |